

REMARKS

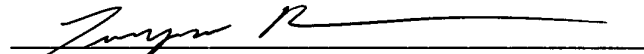
The abstract has been amended to be placed in the form of one paragraph as requested by the Examiner. The specification has been amended in order to correct grammatical and idiomatic errors contained therein. No new matter has been added.

In response to the Examiner's objection to Claim 1, it has been amended to place it in proper form. No new matter has been added.

Claims 1-4 have been rejected under 35 USC 103(a) as being obvious over WO 2004/111287 in view of Kato et al. In order to overcome this rejection, Applicants are enclosing herewith a certified English translation of the foreign priority document which establishes the present application's effective filing date of April 5, 2004. Since the effective date of WO 2004/111287 as a reference is December 23, 2004, this publication is not available as a reference against the present application. As such, it is respectfully submitted that the rejection of the currently presented claims over the prior art has been overcome.

If the Examiner feels that there are any outstanding matters left to be resolved in the present application, she is respectfully requested to contact the undersigned in order that they may be dealt with. Favorable consideration of the present application and the passing of it to issue is respectfully solicited.

Respectfully submitted,



Terryence F. Chapman

TFC/smd

FLYNN, THIEL, BOUTELL
& TANIS, P.C.
2026 Rambling Road
Kalamazoo, MI 49008-1631
Phone: (269) 381-1156
Fax: (269) 381-5465

Dale H. Thiel	Reg. No. 24	323
David G. Boutell	Reg. No. 25	072
Terryence F. Chapman	Reg. No. 32	549
Mark L. Maki	Reg. No. 36	589
Liane L. Churney	Reg. No. 40	694
Brian R. Tumm	Reg. No. 36	328
Steven R. Thiel	Reg. No. 53	685
Donald J. Wallace	Reg. No. 43	977
Sidney B. Williams, Jr.	Reg. No. 24	949

Encl: Replacement Abstract
Certified English Translation of Priority Document
Postal Card

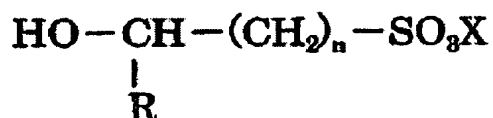


ELECTROLESS GOLD PLATING LIQUID

ABSTRACT

The object is to provide an electroless gold plating liquid which has an adequate deposition speed for practical use without containing any thallium or other heavy metal ions, ~~and which has excellent stability of the plating liquid.~~
~~An electroless gold plating liquid comprising and contains~~ a non-cyanide gold salt as a gold salt, an alkali metal salt or an ammonium salt of sulfurous acid and thiosulfuric acid as a metal complexing agent, a hydroxyalkylsulfonic acid or a salt thereof represented by the following general formula as a reducing agent, and an amine compound-.

{Chemical Formula 1}



{wherein R represents hydrogen, a carboxyl group, or any of a phenyl group, a tolyl group, a naphthyl group, a saturated or unsaturated alkyl group, an acetyl group, an acetonyl group, a pyridyl group and a furyl group which may have a substitutional group, X represents any of hydrogen, Na, K, and NH₄, and n is an integer between 0 and 4.}